OKOS

SCANNING ACOUSTIC MICROSCOPE

VUE 400-P-NexGen

- Semiconductors Package Failure Analysis Voids
- Disbonds
- Cracks
- Delamination
- Internal Defects

Customer Interface
Dual 22" HD LED Monitors

Fixtures
Tray Fixture

Instrumentation
Digital Pulse Receiver
Ultrasonic Digitizer (Max 12 GHz)

Usert Experience Elements
Dual JEDEC Trays
HD LED Lighting
Stainless Steel Tank

Maintenance Free Scan Axis

Motor:	Quad Linear Servo
Max.Velocity:	1500mm/s
Accuracy & Repeatability:	+/- 0.5 micron

Scan Length:	400 mm
Step Length:	380 mm
Focus Length:	35 mm
C-Scan Area:	360 mm x 350 mm
T-Scan Area:	360 mm x 220 mm
Weight:	250 kg

SCANNING ACOUSTIC MICROSCOPE

VUE 250P-NexGen

- Semiconductors Package Failure Analysis Voids
- Disbonds
- Cracks
- Delamination
- Internal Defects

Customer Interface
Dual 22" HD LED Monitors

Fixtures
Open Tank Bed

Instrumentation
Digital Pulse Receiver
Ultrasonic Digitizer (Max 4 GHz)

Usert Experience Elements
HD LED Lighting
Stainless Steel Tank

Maintenance Free Scan Axis

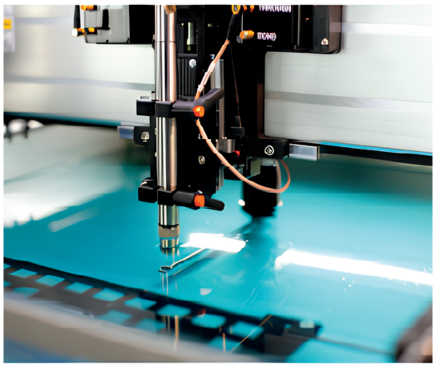
Motor:	Linear Servo
Max.Velocity:	500mm/s
Accuracy & Repeatability:	+/- 0.5 micron
Scan Envelope	322.6 mm

Low Maintenance Step Axis

Step Envelope:	136 mm

Low Maintenance Focus Axis

Focus Envelope:	35 mm



Dimension	700 mm x 560 mm x 470 mm (W X D X H)
Weight	81 kg

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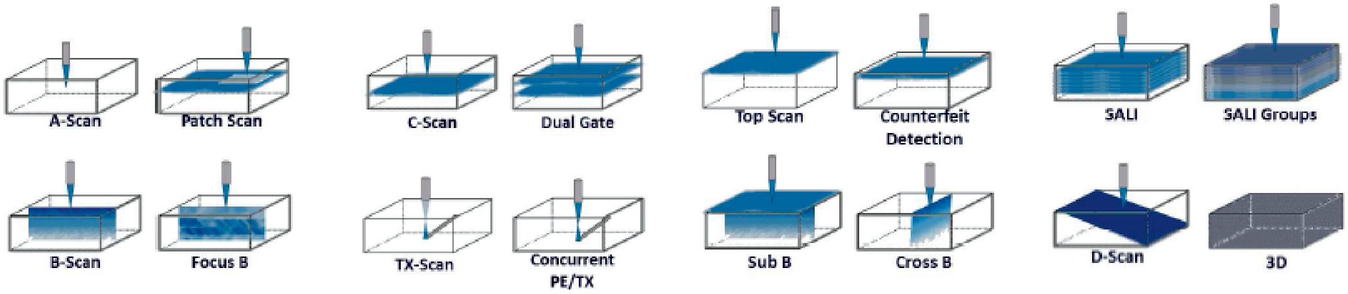
OKOS Digital Imaging System (ODIS)

Full Jedec Tray Inspection



MACROVUE-P imaging power surpasses modern standards delivering premium FA Lab features to semiconductor fabrication facilities.

ODIS is the latest Acoustic Microscopy Software with rich technical content-built to current platforms and industry feedback. Advanced analysis is provided through quantitative tools for measurement and classification parts.

The Analysis version of **ODIS** allows non-scanning computers to virtually scan and analyze data simultaneous real-time analysis or post collection review.

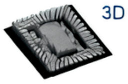
Includes Software Models

- ☑ Basic (user friendly)
- ☑ Advanced (detailed analysis)
- ☑ Production (automated scanning)
- ☑ Offline analysis (virtual scanning)

Application Specific Transducers

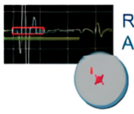
- ☑ Application Specific transducers for the highest quality resolution.
- ☑ Multiple transducers design for enhanced scan capability.


Advanced Time-of-Flight & Thickness Measurements


3D Imaging


Threshold Mapping (post processing)


Void Gating (real-time)


Real-time A-scan & A-scan Capture


C-scan with Multi-gate SALI & SALI Groups


B-scan & SLICE


Cluster Analysis (post processing)

Assuring you our best, always!

For more info, visit www.qesnet.com or email us at marketing@qesnet.com